GBCS SCHEME

USN						17NT73

Seventh Semester B.E. Degree Examination, Jan./Feb. 2021 **MEMS and NEMS**

Max. Marks: 100 Time: 3 hrs.

	No	ote: Answer any FIVE full questions, choosing ONE full question from each mo	dule.
1	a.	Module-1 Explain the four types of MEMS packaging.	(10 Marks)
	b.	Differentiate between MEMS and IC's. OR	(10 Marks
2	a.	Explain the working principle of piezo resistive sensors and piezo ink jet printer.	(10 Marks
	b.	Write notes on: (i) Micro-fluids (ii) RF-MEMS Module-2	(10 Marks
3	a.	Define transducer. Explain the working of capacitive transducers.	(10 Marks
	b.	Explain the importance of cantilever based transducer. OR	(10 Marks
4	a.	Explain the working principle of: (i) Electrochemical Transducer	
		(ii) Bipolar Junction Transducer	(10 Mark
	b.	Write a note on Acoustic Wave Transducers.	(10 Mark
		Madula 3	
5		Module-3 List and explain the various etching methods.	(10 Mark
5	a. b.	Differentiate between Surface and Bulk Micro Machining.	(10 Mark
		OR	(10.3%
6	a.	With a neat sketch, explain the concept of photolithography.	(10 Mark (10 Mark
	b.	Describe the thin film techniques and give the applications. Module-4	(10 Man
7	a.	Define packaging and explain the various packaging technologies.	(10 Marl
	b.	Discuss the working of signal amplifiers and signal conditioning.	(10 Marl
	,	OR	
8	a.	Explain the concept of reliability and stability.	(10 Marl
	b.	Enumerate the concept of: (i) CMOS (ii) Transmitters	(10 Mar
		Module-5	(10 M)
9	a.	Define NEMS. Explain Nano Machining of NEMS.	(10 Mari (10 Mari
	b.	Explain large scale integration of NEMS devices.	(10 Mail
		OR	
10	a.	Explain electron beam lithography with neat sketch.	(10 Mar
	b.	Explain briefly the future challenges and applications of NEMS.	(10 Mar

Important Note: 1. On completing your answers, compulsorily draw diagonal cross lines on the remaining blank pages.